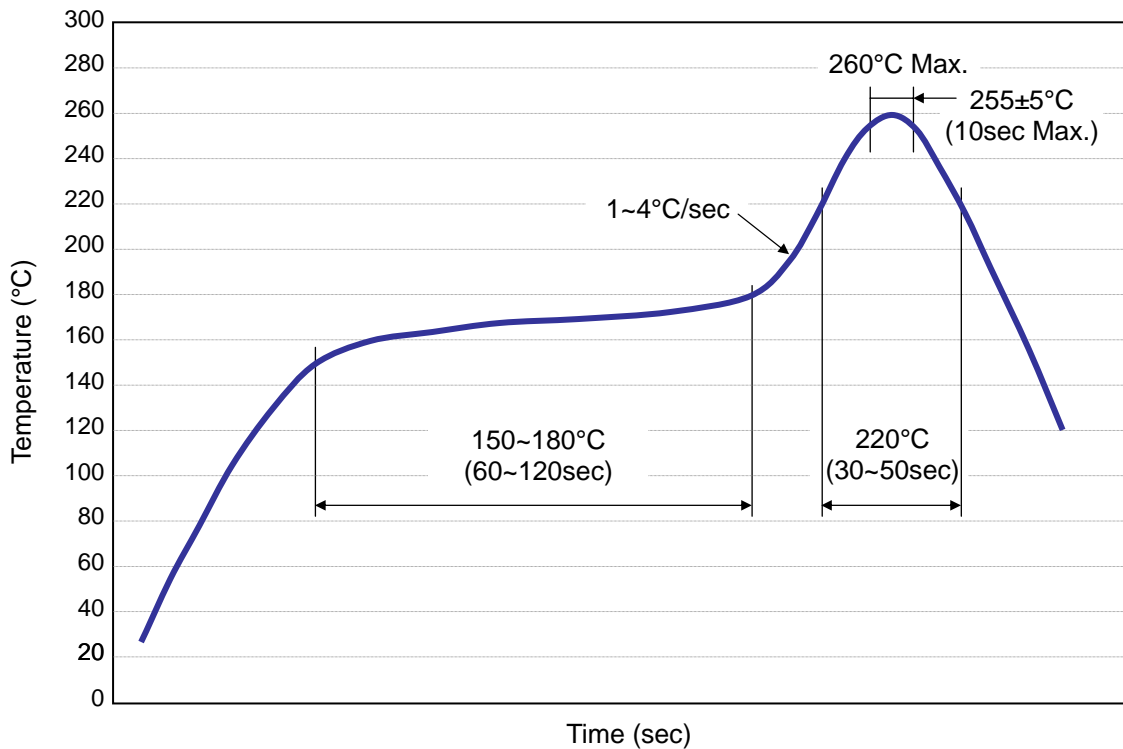




## Lead-Free Reflow Soldering Temperature Profile



Reflow portion	
Peak temperature / Time	260°C (255±5°C) / within 10sec
Above 220°C	30~50sec
Pre-heat portion	
150~180°C	60~120sec
Testing point	Product surface
Product storage condition	10~40°C, within 30~60%RH

Note : While using the above recommended reflow temperature with the solder paste, please limit this process to 3 times only.